

IN THE SPECIFICATION

Please amend the specification as follows:

The paragraph at page 8, line 12 is amended as follows:

Figures 5 and 6 show a wafer holder cleaning apparatus 500 and a wafer holder 300, which in the illustrated embodiment is shown as a spindle chuck, according to the teachings of the present invention. Apparatus 500 includes a support 502 connected to the unit of the fabrication station 206 in which the wafer holder 300 is positioned. In an embodiment, the support 502 is fixed to the unit of the fabrication station. In an embodiment, the support 502 is a wafer handling robot of the transfer system 208. In an embodiment, the support 502 is an arm of a wafer handling robot. A movable joint 504 connects a proximal end of arm 506 to the support 502. A cleaning head assembly 508 is connected to a distal end of arm 506 and is capable of removing contaminants from a wafer holder. In an embodiment, the wafer holder 300 is harder than the cleaning assembly 508. In an embodiment, the joint 504 moves the arm 506 and cleaning head assembly 508 vertically. In an embodiment, the joint 504 moves the arm 506 and cleaning head assembly 508 both vertically and rotationally. In an embodiment, the joint 504 moves the arm 506 and cleaning head assembly 508 in the X, Y, and Z directions. In an embodiment, the joint 504 includes motors, such as stepper motors, and actuators, such as fluid, e.g. hydraulic and pneumatic, actuators to move the arm 506 and assembly 508.